

Product Change Notification / ALAN-20BLUP482

Date:

07-Nov-2022

Product Category:

32-bit Microcontrollers

PCN Type:

Manufacturing Change

Notification Subject:

CCB 4847 Final Notice: Qualification of ATP7 as an additional assembly site for selected Atmel ATSAMD51Jxx and ATSAME5xx device families available in 64L VQFN (9x9x1.0mm) package.

Affected CPNs:

ALAN-20BLUP482_Affected_CPN_11072022.pdf ALAN-20BLUP482_Affected_CPN_11072022.csv

Notification Text:

PCN Status: Final Notification

PCN Type:Manufacturing Change

Microchip Parts Affected:Please open one of the files found in the Affected CPNs section. Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change:Qualification of ATP7 as an additional assembly site for selected Atmel ATSAMD51Jxx and ATSAME5xx device families available in 64L VQFN (9x9x1.0mm) package.

Pre and Post Change Summary:

Pre Change	Post Change	
	Dece 1 of 2	

				Amkor Technology
Assembly location		ASE Inc. (ASE)	ASE Inc. (ASE)	Philippines (P3/P4),
				INC. (ATP7)
Bond Wire	e Material	CuPdAu	CuPdAu	CuPdAu
Die Attacl	n Material	EN-4900F	EN-4900F	CRM1085A
	Compound erial	G631H	G631H	G631BQF
	Material	C194	C194	C194
Lead-Frame	Paddle Size	193 X 193 mils	193 X 193 mils	197X197 mils
		See pre and	post change comparis	on

Impacts to Data Sheet:None

Change ImpactNone

Reason for Change:To improve manufacturability and on-time delivery performance by qualifying ATP7 as an additional assembly site.

Change Implementation Status: In Progress

Estimated First Ship Date: December 9, 2022 (date code: 2250)

Note: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Time Table Summary:

	September 2021			>	November 2022			2	December 2022						
Workweek	3 6	3 7	3 8	3 9	4 0		4 5	4 6	4 7	4 8	4 9	50	51	52	53
Initial PCN Issue Date				x											
Qual Report Availability								x							
Final PCN Issue Date								×							
Estimated												х			

Implementation Date

Method to Identify Change: Traceability code

Qualification Report: Please open the attachments included with this PCN labeled as PCN_#_Qual_Report.

Revision History:September 23, 2021: Issued initial notification. November 7, 2022: Issued final notification. Attached the Qualification Report. Provided estimated first ship date to be on December 9, 2022.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachments:

PCN_ALAN-20BLUP482 Pre and Post Change_Summary.pdf PCN_ALAN-20BLUP482_Qualification Report.pdf

Please contact your local Microchip sales office with questions or concerns regarding this notification.

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QUALIFICATION REPORT RELIABILITY LABORATORY

PCN #: ALAN-20BLUP482

Date September 14, 2022

Qualification of ATP7 as an additional assembly site for selected Atmel ATSAMD51Jxx and ATSAME5xx device families available in 64L VQFN (9x9x1.0mm) package.



- **Purpose:** Qualification of ATP7 as an additional assembly site for selected Atmel ATSAMD51Jxx and ATSAME5xx device families available in 64L VQFN (9x9x1.0mm) package.
- **CCB**: 4847

Misc.FisceFitBD NumberTBDMP Code (MPC)651067TMBC05Part Number (CPN)ATSAMD51J20A-MUMSL. informationMSL-3 @260CAssembly Shipping Media (T/R, Tube/Tray)KS-870274Base Quantity Multiple (BQM)Tray -260Reliability SiteMPHILPaddle size197X197 (5X5mm)MaterialC194FHDAP Surface PrepDouble Ring PlatingTreatmentRoughenedProcessEtchedLead-Iock (With Locking Holes)NoPart Number101419822Lead PlatingMatte SnStrip Size250 X 70mmMaterialCuPdAuBond WirePart NumberPart NumberCRM1085ADie AttachConductivePKGPin/Ball CountPKG width/size9x9x1mm		Assembly site	ATP7			
Misc.MP Code (MPC)651067TMBC05Part Number (CPN)ATSAMD51J20A-MUMSL informationMSL-3 @260CAssembly Shipping Media (T/R, Tube/Tray)KS-870274Base Quantity Multiple (BQM)Tray -260Reliability SiteMPHILPaddle size197X197 (5X5mm)MaterialC194FHDAP Surface PrepDouble Ring PlatingTreatmentRoughenedProcessEtchedLead-FrameLead-lock (With Locking Holes)Part Number101419822Lead PlatingMatte SnStrip Size250 X 70mmBend WirePart NumberDie AttachConductiveYesMaterialPKGPir/Ball CountPKGPin/Ball CountPin/Ball Count64		,				
Misc.Part Number (CPN)ATSAMD51J20A-MUMSL informationMSL-3 @260CAssembly Shipping Media (T/R, Tube/Tray)KS-870274Base Quantity Multiple (BQM)Tray -260Reliability SiteMPHILPaddle size197X197 (5X5mm)MaterialC194FHDAP Surface PrepDouble Ring PlatingTreatmentRoughenedProcessEtchedLead-lock (With Locking Holes)NoPart Number101419822Lead PlatingMatter SnStrip Size250 X 70mmMaterialCuPdAuDie AttachConductiveYesPart NumberMaterialCuPdAuPhin/Ball Count64						
Misc.MSL informationMSL-3 @260CAssembly Shipping Media (T/R, Tube/Tray)KS-870274Base Quantity Multiple (BQM)Tray -260Reliability SiteMPHILPaddle size197X197 (5X5mm)MaterialC194FHDAP Surface PrepDouble Ring PlatingTreatmentRoughenedProcessEtchedLead-FrameLead-lock (With Locking Holes)NoPart NumberPart Number101419822Lead PlatingMaterialCuPdAuCuPdAuBond WirePart NumberDie AttachConductiveMCPart NumberPKG TypeVQFNPKGPin/Ball Count						
Assembly Shipping Media (T/R, Tube/Tray)KS-870274Base Quantity Multiple (BQM)Tray -260Reliability SiteMPHILPaddle size197X197 (5X5mm)MaterialC194FHDAP Surface PrepDouble Ring PlatingTreatmentRoughenedProcessEtchedLead-Iock (With Locking Holes)NoPart Number101419822Lead PlatingMatte SnStrip Size250 X 70mmMaterialCuPdAuDie AttachConductivePKGPart NumberPKG TypeVQFNPKGPin/Ball Count	<u>Misc.</u>	· · · · ·				
Reliability SiteMPHILPaddle size197X197 (5X5mm)MaterialC194FHDAP Surface PrepDouble Ring PlatingTreatmentRoughenedProcessEtchedLead-lock (With Locking Holes)NoPart Number101419822Lead PlatingMatte SnStrip Size250 X 70mmBond WirePart NumberDie AttachConductiveMCPart NumberPKGPKG TypePKGPin/Ball Count		Assembly Shipping Media				
Paddle size197X197 (5X5mm)MaterialC194FHDAP Surface PrepDouble Ring PlatingTreatmentRoughenedProcessEtchedLead-lock (With Locking Holes)NoPart Number101419822Lead PlatingMatte SnStrip Size250 X 70mmMaterialCuPdAuDie AttachConductiveYesYesMCPart NumberPKGPin/Ball CountPin/Ball Count64		Base Quantity Multiple (BQM)	Tray -260			
MaterialC194FHDAP Surface PrepDouble Ring PlatingTreatmentRoughenedProcessEtchedLead-lock (With Locking Holes)NoPart Number101419822Lead PlatingMatte SnStrip Size250 X 70mmMaterialCuPdAuDie AttachConductiveYesYesMCPart NumberPKGPin/Ball CountPKGPin/Ball Count		Reliability Site	MPHIL			
Lead-FrameDAP Surface PrepDouble Ring PlatingTreatmentRoughenedProcessEtchedLead-lock (With Locking Holes)NoPart Number101419822Lead PlatingMatte SnStrip Size250 X 70mmBond WirePart NumberPart NumberCRM1085ADie AttachConductiveMCPart NumberPKGPin/Ball CountPin/Ball Count64		Paddle size	197X197 (5X5mm)			
Lead-FrameTreatmentRoughenedProcessEtchedLead-lock (With Locking Holes)NoPart Number101419822Lead PlatingMatte SnStrip Size250 X 70mmMaterialCuPdAuDie AttachConductiveMCPart NumberPKGPin/Ball CountPKGPin/Ball Count		Material	C194FH			
Lead-FrameProcessEtchedLead-lock (With Locking Holes)NoPart Number101419822Lead PlatingMatte SnStrip Size250 X 70mmBond WireMaterialPart NumberCuPdAuDie AttachConductiveMCPart NumberPKGPin/Ball CountPin/Ball Count64		DAP Surface Prep	Double Ring Plating			
Lead-FrameLead-lock (With Locking Holes)NoPart Number101419822Lead PlatingMatte SnStrip Size250 X 70mmBond WireMaterialPart NumberCuPdAuDie AttachConductivePart NumberG631BQFMCPKG TypePKGPin/Ball CountPKGPin/Ball Count		Treatment	Roughened			
Lead-PraineHoles)NoPart Number101419822Lead PlatingMatte SnStrip Size250 X 70mmBond WireCuPdAuPart NumberCRM1085ADie AttachConductivePart NumberG631BQFMCPin/Ball CountPKGPin/Ball Count		Process	Etched			
Lead PlatingMatte SnStrip Size250 X 70mmBond WireCuPdAuPart NumberCRM1085ADie AttachConductivePart NumberG631BQFMCPKG TypeVQFNPKGPin/Ball Count64	<u>Lead-Frame</u>		No			
Strip Size250 X 70mmMaterialCuPdAuBond WirePart NumberPart NumberCRM1085ADie AttachConductiveYesYesMCPart NumberPKG TypeVQFNPKGPin/Ball Count64		Part Number	101419822			
Bond WireMaterialCuPdAuBond WirePart NumberCRM1085ADie AttachConductiveYesMCPart NumberG631BQFPKG TypeVQFNPKGPin/Ball Count64		Lead Plating	Matte Sn			
Bond WirePart NumberCRM1085ADie AttachConductiveYesMCPart NumberG631BQFPKG TypeVQFNPKGPin/Ball Count64		Strip Size	250 X 70mm			
Part NumberCRM1085ADie AttachConductiveYesMCPart NumberG631BQFPKG TypeVQFNPKGPin/Ball Count64		Material	CuPdAu			
Die AttachConductiveYesMCPart NumberG631BQFPKG TypeVQFNPKGPin/Ball Count64	Bond Wire					
MC Part Number G631BQF PKG Type VQFN PKG Pin/Ball Count 64		Part Number	CRM1085A			
MC PKG Type VQFN PKG Pin/Ball Count 64	<u>Die Attach</u>	Conductive	Yes			
PKG Pin/Ball Count 64	MC	Part Number	G631BQF			
		PKG Type	VQFN			
PKG width/size 9x9x1mm	<u>PKG</u>	Pin/Ball Count	64			
		PKG width/size	9x9x1mm			



Manufacturing Information

Assembly Lot No.
ATP7225100059.000
ATP7225100060.000
ATP7225200001.000

Result



Fail

65106 from UMC 65nm in 64L VQFN 9x9x1.0mm assembled at ATP7.pass reliability test per QCI-39000 which was conducted at MPHL rel lab. This package is qualified Moisture/Reflow Sensitivity Classification Level 3 at 260°C reflow temperature per IPC/JEDEC J-STD-020E standard.

PACKAGE QUALIFICATION REPORT										
Test Number (Reference)	Test Condition	Standard/ Method	Qty. (Acc.)	Def/SS	Result	Remarks				
Precondition Prior Perform Reliability Tests	Electrical Test :25°C Magnum	JESD22- A113,	231 per lot	Lot 1 0/231	Pass	Good Devices				
(At MSL Level 3)		JIP/ IPC/JEDE C J-STD-		Lot 2 0/231	Pass					
		020E		Lot 3 0/231	Pass					
	Bake 150°C, 24 hrs System: HERAEUS		231 per lot							
	Moisture Soak 192h(30°C/60%RH) System: Climats Excal 5423-HE		231 per lot							
	Reflow 3x Convection-Reflow 265°C max System: Mancorp CR.5000F	-	231 per lot	Lot 1 0/231	Pass					
				Lot 2 0/231	Pass					
				Lot 3 0/231	Pass					
	Electrical Test :25°C Magnum SV 1024		231 per lot	Lot 1 0/231	Pass					
				Lot 2 0/231	Pass					
				Lot 3 0/231	Pass					

	PACKAGE QUALIFICATION REPORT										
Test Number (Reference)	Test Condition	Standard/ Method	Qty. (Acc.)	Def/SS.	Result	Remarks					
UNBIASED HAST	Stress Condition: (Standard) + 130°C, 85%RH, 96 hrs. System: HIRAYAMA HASTEST PC-422R8	JESD22- A118	77 units per lot	Lot 1 0/77 Lot 2	Pass	Parts had been pre-conditioned at 260°C					
	Electrical Test: 25°C			0/77 Lot 3	Pass						
	System: Magnum		77	0/77							
	Stress Condition: (Standard) + 130°C, 85%RH, 192 hrs. System: HIRAYAMA HASTEST PC-422R8	JESD22- A118	77 units per lot	Lot 1 0/77	Pass						
	Electrical Test: 25°C			Lot 2 0/77 Lot 3	Pass						
	System: Magnum			0/77	Pass						
	Internal Package Analysis		5 units per lot	Lot 1, 0/5	Pass						
				Lot 2, 0/5	Pass						
				Lot 3, 0/5	Pass						

	PACKAGE QUALIFIC	ATION	I REP	ORT		
Test Number (Reference)	Test Condition	Standard/ Method	Qty. (Acc.)	Def/SS.	Result	Remarks
HAST	Stress Condition: (Standard) 130°C, 85%RH, 96 hrs. VOLTS=3.6V	JESD22- A110	77 units per lot	Lot 1 0/77	Pass	
	System: HIRAYAMA HASTEST PC-422R8			Lot 2 0/77	Pass	
	Electrical Test: 25°C System: Magnum			Lot 3 0/77	Pass	
	Stress Condition: (Standard) 130°C, 85%RH, 192 hrs. VOLTS=3.6V	JESD22- A110	77 units per lot	Lot 1 0/77	Pass	
	System: HIRAYAMA HASTEST PC-422R8			Lot 2 0/77	Pass	
	Electrical Test: 25°C System: Magnum			Lot 3 0/77	Pass	
	Internal Package Analysis		5 units per lot	Lot 1, 0/5	Pass	
				Lot 2, 0/5	Pass	
				Lot 3, 0/5	Pass	

	PACKAGE QUA	LIFICA	FION F	REPORT	•	
Test Number (Reference)	Test Condition	Standard/ Method	Qty. (Acc.)	Def/SS	Result	Remarks
Temp Cycle	Stress Condition: (Standard) - 65°C/150°C, 500 Cycles System : Votsch VTS ² 7012 Electrical Test: 25°C System: Magnum	JESD22- A104	77 units per lot	Lot 1 0/77 Lot 2 0/77 Lot 3 0/77	Pass Pass Pass	Parts had been pre- conditioned at 260°C
	Stress Condition: (Standard) - 65°C/150°C, 1000 Cycles System : Votsch VTS ² 7012 Electrical Test: 25°C System: Magnum	JESD22- A104	77 units per lot	Lot 1 0/77 Lot 2 0/77 Lot 3 0/77	Pass Pass Pass	
	Internal Package Analysis		5 units per lot	Lot 1, 0/5 Lot 2, 0/5 Lot 3, 0/5	Pass Pass Pass	
	Bond Strength: System: Dage Wire Bond Pull (> 2 grams) Wire Ball <i>Shear (>9.1 grams)</i> System: Dage	MILSTD883-2 Method 2011.10 AEC Q100.001	5 units, 30 bonds per lot	Lot 1 0/30 Lot 2 0/30 Lot 3 0/30	Pass Pass Pass	
High Temperature Storage Life	Stress Condition: Bake 175°C, 5000 hrs System: HERAEUS Electrical Test: 25°C System: Magnum	JESD22- A103	45 units per lot	Lot 1 0/45 Lot 2 0/45 Lot 3 0/45	Pass Pass Pass	

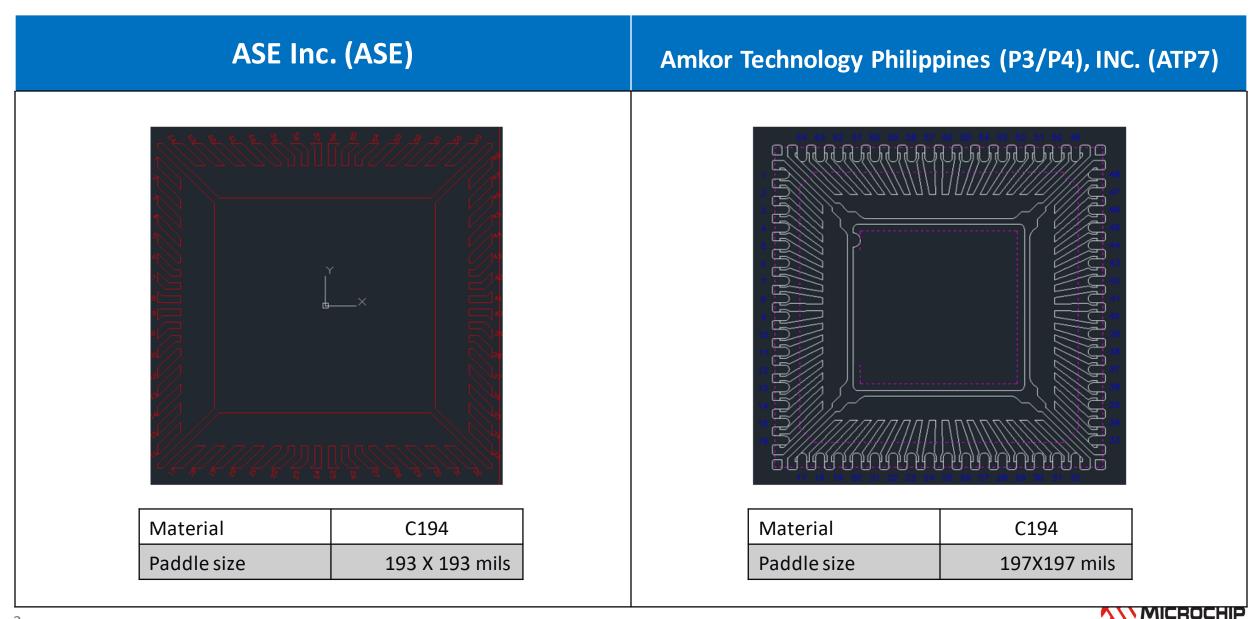
PACKAGE QUALIFICATION REPORT										
Test Number (Reference)	Test Condition	Standard/ Method	Qty. (Acc.)	Def/SS.	Result	Remarks				
Bond Strength, 0 Hour	Bond Strength:	MILSTD883-2 Method 2011.10	5 units, 30 bonds	Lot 1 0/30	Pass					
	Wire Bond Pull (> 2 grams) Wire Ball <i>Shear (>9.1 grams)</i>	AEC Q100.001	per lot	Lot 2 0/30	Pass					
	System: Dage			Lot 3 0/30	Pass					
Physical Dimensions		JESD22 B100 and B108	10 units per lot	0/30						
Standard Pb- free Solderability	> 95% lead coverage	J-STD-002D	22 units 1 lot	0/22	Pass					

CCB 4847 Pre and Post Change Summary PCN# ALAN-20BLUP482

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Pre and Post Change Summary



2

Affected Catalog Part Numbers(CPN)

ATSAME51J19A-MU ATSAME51J18A-MU ATSAMD51J18A-MU ATSAMD51J19A-MU ATSAMD51J20A-MU ATSAME53J18A-MU ATSAME53J19A-MU ATSAME53J20A-MU ATSAME51J20A-MU ATSAMD51J18A-MU-EFP ATSAMD51J19A-MU-EFP ATSAMD51J20A-MU-EFP ATSAME51J18A-MU-EFP ATSAME51J19A-MU-EFP ATSAME51J20A-MU-EFP ATSAME53J18A-MU-EFP ATSAME53J19A-MU-EFP ATSAME53J20A-MU-EFP ATSAMD51J19A-MUN01 ATSAME53J18A-MUN02 ATSAME51J19A-MUT ATSAME51J18A-MUT ATSAMD51J18A-MUT ATSAMD51J19A-MUT ATSAMD51J20A-MUT ATSAME53J18A-MUT ATSAME53J19A-MUT ATSAME53J20A-MUT ATSAME51J20A-MUT ATSAMD51J18A-MUT-EFP ATSAMD51J19A-MUT-EFP ATSAMD51J20A-MUT-EFP ATSAME51J18A-MUT-EFP ATSAME51J19A-MUT-EFP ATSAME51J20A-MUT-EFP ATSAME53J18A-MUT-EFP ATSAME53J19A-MUT-EFP ATSAME53J20A-MUT-EFP ATSAMD51J19A-MUTN01